

FINAL PRODUCT/PROCESS CHANGE NOTIFICATION #16952

Generic Copy

Issue Date: 20-Dec-2012

<u>TITLE</u>: Final PCN for wafer fabrication transfer from Gifu to AMPI and changing wire from gold to copper and changing part number from CPH3350-TL-H to CPH3350-TL-W.

PROPOSED FIRST SHIP DATE: 20-Mar-2013

AFFECTED CHANGE CATEGORY(S): Wafer Fabrication Location Change and Assembly area-Wire Bonding and Part number change

FOR ANY QUESTIONS CONCERNING THIS NOTIFICATION:

Contact your local ON Semiconductor Sales Office or Toshikazu.Hirai@onsemi.com

SAMPLES: Contact your local ON Semiconductor Sales Office or Katsuya.lto@onsemi.com

ADDITIONAL RELIABILITY DATA: May be available

Contact your local ON Semiconductor Sales Office or Yasuhiro.lgarashi@onsemi.com.

NOTIFICATION TYPE:

Final Product/Process Change Notification (FPCN)

Final change notification sent to customers. FPCNs are issued at least 90 days prior to implementation of the change.

ON Semiconductor will consider this change approved unless specific conditions of acceptance are provided in writing within 30 days of receipt of this notice. To do so, contact <quality@onsemi.com>

DESCRIPTION AND PURPOSE:

This is a Final Process Change Notification to announce for below contents.

- 1) The wafer fabrication transfer from Gifu to AMPI
- 2) Changing wire from gold to copper
- 3) Changing part number from CPH3350-TL-H to CPH3350-TL-W.

CPH3350-TL-H: AMPI wafer with Gold wire CPH3350-TL-W: AMPI wafer with Copper wire

The product design and electrical specifications will remain identical. A full electrical characterization over the temperature range will be performed for each product to check the device functionality and electrical specifications. Qualification tests are designed to show that the reliability of transferred devices will continue to meet or exceed ON Semiconductor standards.

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QUALIFICATION PLAN:

Test:	Conditions:	Interval:	Results
High Temperature Storage	Ta=150degC	1000 hrs	PASS
Temp Humidity Storage	Ta=85degC, RH=85%	1000 hrs	PASS
Steady State Operating Life	Tj=150degC	1000 hrs	PASS
High Temperature Reverse Bias	Ta=150degC,VDSS=20V	1000 hrs	PASS
Temperature Cycle	Ta=-55degC to 150degC 30min each	100 cycles	PASS
Pressure Cooker	Ta=121degC,2.03×10 ⁵ Pa,100%	50 hrs	PASS
Solder Test	Ta=260degC,10s(Solder bath)	10 s	PASS

Notice) %1 Pre-treatment: Resistance to Soldering heat (Flow: 260degC/10s)

%2 Full Electrical Distribution Data

ELECTRICAL CHARACTERISTIC SUMMARY

There is no change in the electrical performance. Datasheet specifications remain unchanged.

List of affected Generic parts:

PART_ID	New PART_ID
CPH3350-TL-H	CPH3350-TL-W

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